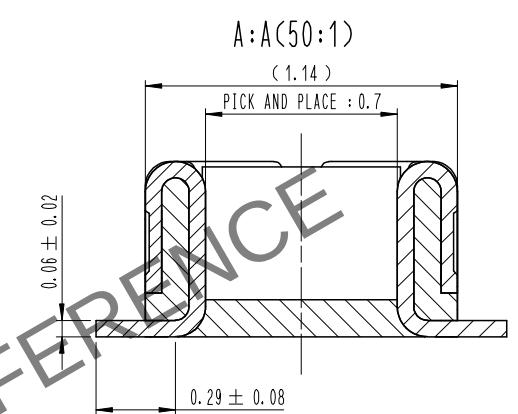
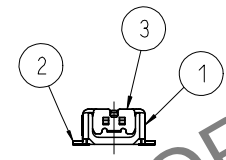
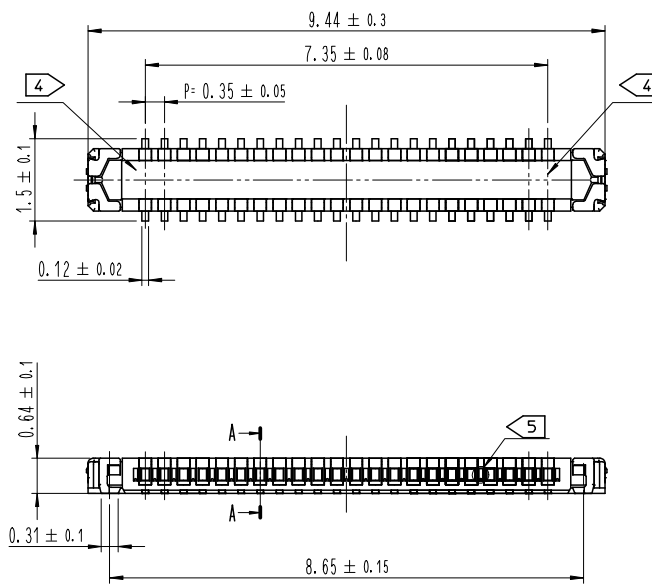
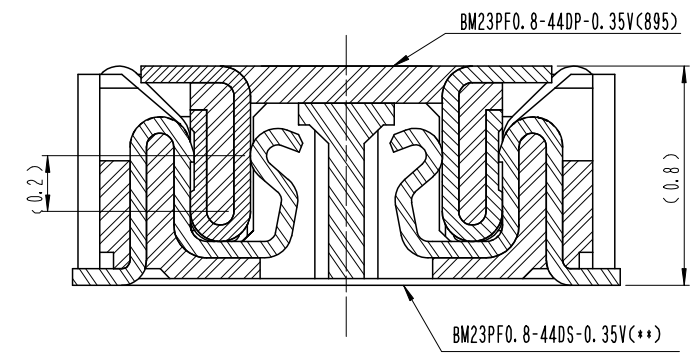




ENGAGEMENT FIGURE (50:1)

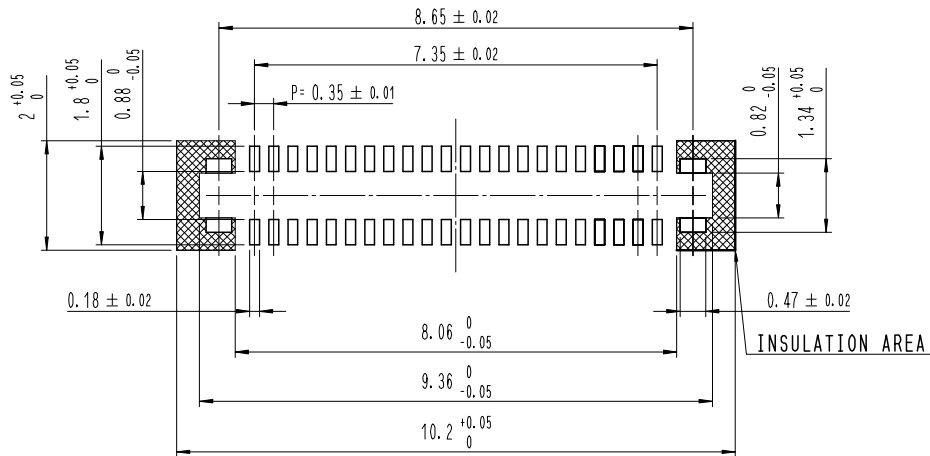


- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDER PLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5. A PART OF THE WALL COULD BE NOTCHED.

△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B Y	檢圖 CHKD	年月日 DATE
△					△				
△					△				
△					△				

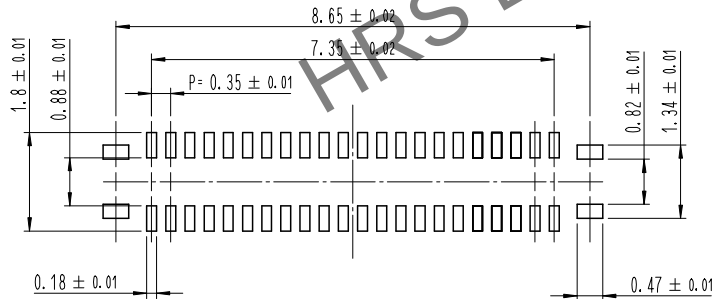
4	PS	CLEAR (EMBOSSED CARRIER TAPE)							
3	COPPER ALLOY	3		7	PS	CLEAR(REINFORCEMENT COLLAR)			
2	COPPER ALLOY	2		6	PS	BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS			
REMARKS					DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
					S. H. PARK 20.04.09	S. H. PARK 20.04.09	H. W. JO 20.04.09	H. W. JO 20.04.09	20.04.09
CODE NO. (OLD)			DRAWING NO. EDC3-632594-95		PART NO. BM23PF0.8-44DP-0.35V(895)				
					SCALE 10:1		 HIROSE KOREA CO., LTD.		CODE NO CL 6644-0064-7-895
UNITS mm									

7 RECOMMENDED PCB LAYOUT

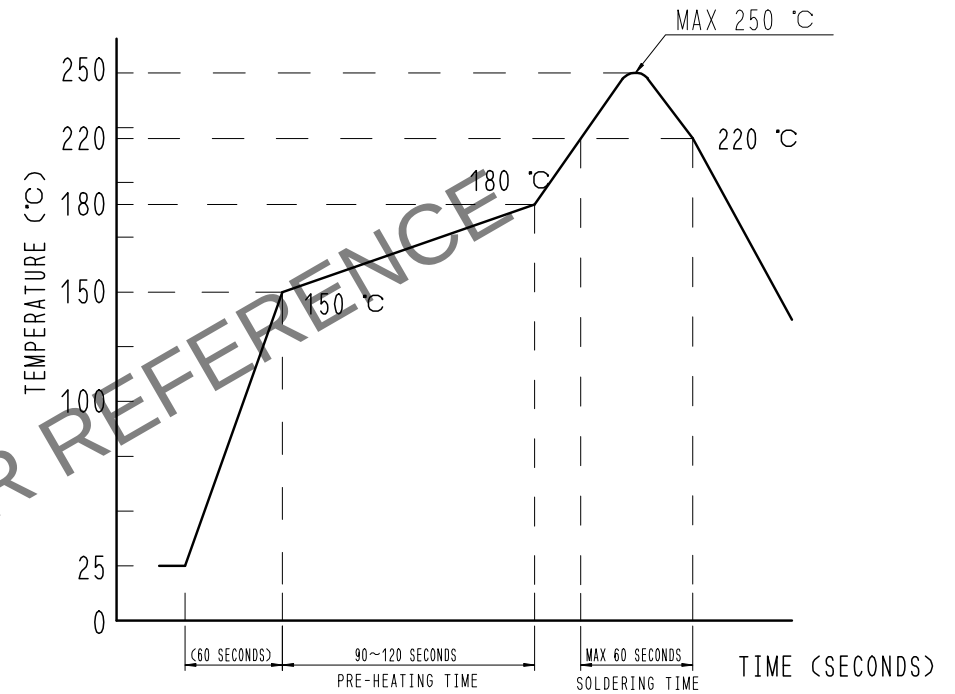


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N_2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.

(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE (MIN): 150 $^{\circ}\text{C}$

PRE-HEAT TEMPERATURE (MAX): 180 $^{\circ}\text{C}$

PRE-HEAT TIME: 90~120 SEC.

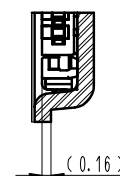
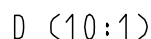
- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632594-95	PART NO.	BM23PF0. 8-44DP-0. 35V(895)	
	SCALE	10:1	CODE NO	CL 6644-0064-7-895	2/3
	UNITS	mm	HIROSE KOREA CO., LTD.		

C-C (5:1)



10 TAPING(FREE)



 SCALE 10:1 UNITS mm	DRAWING NO. EDC3-632594-95		PART NO. BM23PF0.8-44DP-0.35V(895)	
	 HIROSE KOREA CO., LTD.		CODE NO. CL 6644-0064-7-895	